



PK520 (v1.1) December 27, 2011

100% Material Declaration Data Sheet for Spartan®-3/-3E/-3A FT256 (Cu Wire)

Average Weight: 0.7690g

| Component | Substance Description | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|----------------------|-----------------------|---------------------------|-------------------------|----------------|--------------------------------------------|----------------------------|
| Silicon Die | | | | | 0.020003 | 2.601 |
| | Silicon (Si) | 7440-21-3 | 100.00 | | 0.020003 | |
| Die Attach | | | | | 0.006372 | 0.829 |
| | Silver (Ag) | 7440-22-4 | 77.50 | | 0.004938 | |
| | Bismaleimide monomer | Trade Secret | 15.00 | | 0.000956 | |
| | Acrylate Monomer | Trade Secret | 7.50 | | 0.000478 | |
| Mold Compound | | | | | 0.382614 | 49.755 |
| | Epoxy Resin | Trade Secret | 5.00 | | 0.019131 | |
| | Phenol Resin | Trade Secret | 3.00 | | 0.011478 | |
| | Phenol Novolac | 9003-35-4 | 3.00 | | 0.011478 | |
| | Metal Hydroxide | Trade Secret | 3.00 | | 0.011478 | |
| | Carbon Black | 1333-86-4 | 0.30 | | 0.001148 | |
| | Silica Fused | 60676-86-0 | 70.40 | | 0.269360 | |
| | Silica Fused | 7631-86-9 | 15.00 | | 0.057392 | |
| | Silica, crystalline | 14808-60-7 | 0.30 | | 0.001148 | |
| Solder Balls | | | | | 0.140093 | 18.218 |
| | Tin (Sn) | 7440-31-5 | 63.00 | | 0.088259 | |
| | Lead (Pb) | 7439-92-1 | 37.00 | | 0.051834 | |
| Copper Wire | | | | | 0.009626 | 1.252 |
| | Copper (Cu) | 7440-50-8 | 98.75 | | 0.009505 | |
| | Palladium | 7440-50-3 | 1.25 | | 0.000120 | |

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| Component | Substance Description | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|-----------|----------------------------|--------------------------------------------------------------------------------------------------------------|-------------------------|----------------|--------------------------------------------|----------------------------|
| Substrate | | | | | 0.210292 | 27.346 |
| | Copper (Cu) | 7440-50-8 | 17.68 | | 0.037190 | |
| | Nickel (Ni) | 7440-02-0 | 4.23 | | 0.008889 | |
| | Gold (Au) | 7440-57-5 | 0.50 | | 0.001061 | |
| | Glass Fiber | 65997-17-3 | 16.27 | | 0.034204 | |
| | Non Halogen Fire Retardant | 1675-54-3 | 0.01 | | 0.000021 | |
| | BT (Core) | 105391-33-1, 25722-66-1, 9003-36-5, 21645-51-2, 7440-50-8 | 46.23 | | 0.097224 | |
| | Solder Mask | 13676-54-5, 25722-66-1, 147-14-8, 7727-43-7, 61790-53-2, 14807-96-6, 461-58-5 7723-14-0 | 15.08 | | 0.031702 | |

Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|----------|---------|------------------------------|
| 09/16/11 | 1.0 | Initial Xilinx release. |
| 12/27/11 | 1.1 | Removal of Arsenic compound. |

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